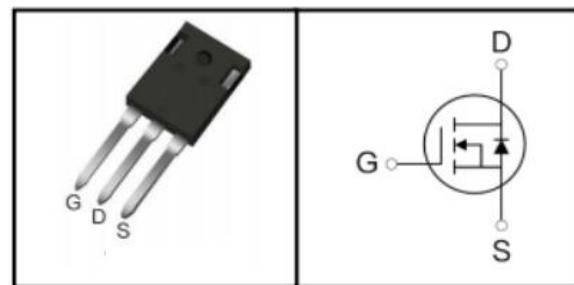


SiC N-Channel MOSFET**FEATURES**

- High blocking voltage with low On-Resistance
- High Speed Switching with Low Capacitance
- Easy to Parallel and Simple to Drive

APPLICATIONS

- Solar Inverters
- Switch Mode Power Supplies
- DC-DC Converters
- Motor drives

**Absolute Maximum Ratings($T_C=25^\circ\text{C}$)**

SYMBOL	PARAMETER	VALUE	UNIT
V_{DSS}	Drain-Source Voltage	1700	V
V_{GSS}	Gate-Source Operation Voltage	-10/+25	V
I_D	Drain Current-Continuous	75	A
	Drain Current-Continuous@ $T_c=100^\circ\text{C}$	48	A
I_{DM}	Drain Current-Single Pulse	160	A
P_D	Total Dissipation @ $T_c=25^\circ\text{C}$	338	W
T_J	Max. Operating Junction Temperature	-40~150	$^\circ\text{C}$
T_{stg}	Storage Temperature	-40~150	$^\circ\text{C}$

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	MAX	UNIT
$R_{th j-c}$	Thermal Resistance, Junction to Case	0.37	$^\circ\text{C}/\text{W}$

SiC N-Channel MOSFET

ELECTRICAL CHARACTERISTICS ($T_c=25^\circ\text{C}$)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP.	MAX	UNIT
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0\text{V}, I_D = 0.1\text{mA}$	1700	--	--	V
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}} = 10\text{V}, I_D = 18\text{mA}$	2.0	--	4.0	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-stage Resistance	$V_{\text{GS}} = 20\text{V}, I_D = 50\text{A}$	--	40	70	$\text{m}\Omega$
		$V_{\text{GS}} = 20\text{V}, I_D = 50\text{A}, T_c = 25^\circ\text{C}$	--	80	--	
I_{GSS}	Gate Source Leakage Current	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$	--	--	600	nA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 1700\text{V}, V_{\text{GS}} = 0\text{V}$	--	2	100	μA
R_G	Internal Gate Resistance	$f = 1 \text{ MHz}, V_{\text{AC}} = 25 \text{ mV}$	--	1.3	--	Ω
g_{fs}	Transconductance	$V_{\text{DS}} = 20 \text{ V}, I_{\text{DS}} = 50 \text{ A}$	--	25	--	S
		$V_{\text{DS}} = 20 \text{ V}, I_{\text{DS}} = 50 \text{ A}, T_J = 150^\circ\text{C}$	--	23.5	--	
C_{iss}	Input Capacitance	$V_{\text{GS}} = 0\text{V}$ $V_{\text{DS}} = 1200\text{V}$ $f = 1.0\text{MHz}$ $V_{\text{AC}} = 25\text{mV}$	--	3455	--	pF
C_{oss}	Output Capacitance		--	171	--	
C_{rss}	Reverse Transfer Capacitance		--	7	--	
Q_g	Total Gate Charge	$V_{\text{DD}} = 1200\text{V}$ $I_D = 50\text{A}$ $V_{\text{GS}} = -5\text{to}+20\text{V}$	--	43	--	nC
Q_{gs}	Gate-Source Charge		--	74	--	
Q_{gd}	Gate-Drain Charge		--	200	--	
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{GS}} = -5\text{to}+20\text{V}$ $I_D = 50\text{A}$ $V_{\text{DS}} = 400\text{V}$ $R_g = 2.5\Omega$ inductive load	--	68	--	ns
t_r	Turn-on Rise Time		--	19	--	
$t_{\text{d}(\text{off})}$	Turn-off Delay Time		--	35	--	
t_f	Turn-off Fall Time		--	19	--	
$C_{\text{o(er)}}$	Effective OutputCapacitance (Energy Related)	$V_{\text{GS}} = 0\text{ V}, V_{\text{DS}} = 0 \dots 1200\text{V}$	--	188	--	pF
$C_{\text{o(tr)}}$	Effective Output Capacitance (Time Related)		--	255	--	

SiC N-Channel MOSFET

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP.	MAX	UNIT
E_{ON}	Turn-On Switching Energy (SiC Diode FWD)	$V_{DS} = 1200 \text{ V}$, $V_{GS} = -5/20 \text{ V}$ $I_D = 50\text{A}$, $R_G = 2.5 \Omega$, $L = 99 \mu\text{H}$ $T_J = 150^\circ\text{C}$ using SiC Diode as FWD	--	2.5	--	mJ
E_{OFF}	Turn Off Switching Energy (SiC Diode FWD)		--	1.4	--	
E_{ON}	Turn-On Switching Energy (SiC Diode FWD)	$V_{DS} = 1200 \text{ V}$, $V_{GS} = -5/20 \text{ V}$ $I_D = 50\text{A}$, $R_G = 2.5 \Omega$, $L = 99 \mu\text{H}$ $T_J = 150^\circ\text{C}$ using MOSFET Diode as FWD	--	4.9	--	
E_{OFF}	Turn Off Switching Energy (SiC Diode FWD)		--	1.1	--	



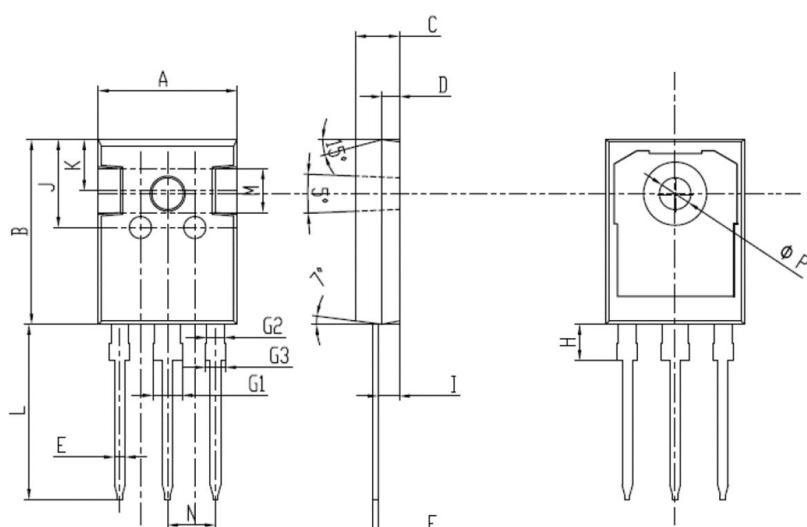
SOURCE-DRAIN BODY DIODE CHARACTERISTICS

Drain - Source Body Diode Characteristics

V_{SD}	Diode Forward Voltage	$I_{SD}=25\text{A}$, $V_{GS} = -5\text{V}$	--	3.8	--	V
		$I_{SD}=25\text{A}$, $V_{GS} = -5\text{V}$, $T_J = 150^\circ\text{C}$	--	3.4	--	
I_S	Continuous Diode Forward Current	$V_{GS} = -5 \text{ V}$, $T_C = 25^\circ\text{C}$	--	--	76	A
t_{rr}	Reverse Recovery Time	$V_{GS} = -5 \text{ V}$, $I_{SD} = 50 \text{ A}$ $V_R = 1200\text{V}$ $dif/dt=1000 \text{ A}/\mu\text{s}$ $T_J = 150^\circ\text{C}$	--	53	--	ns
Q_{rr}	Reverse Recovery Charge		--	461	--	uC
I_{rrm}	Peak Reverse Recovery Current		--	14	--	A
t_{rr}	Reverse Recovery Time	$V_{GS} = -5 \text{ V}$, $I_{SD} = 50 \text{ A}$ $V_R = 1200\text{V}$ $dif/dt=3040 \text{ A}/\mu\text{s}$ $T_J = 150^\circ\text{C}$	--	40	--	ns
Q_{rr}	Reverse Recovery Charge		--	481	--	uC
I_{rrm}	Peak Reverse Recovery Current		--	22	--	A

SiC N-Channel MOSFET

PACKAGE DIMENSIONS (UNIT: mm):
TO-247-3



SYMBOLS	MILLIMETERS	
	MIN	MAX
A	15.50	16.10
B	20.80	21.30
C	4.80	5.20
D	1.85	2.15
E	1.11	1.36
F	0.51	0.75
G1	2.91	3.21
G2	1.85	2.15
G3	1.91	2.21
H	4.00	4.30
I	2.21	2.59
J	9.90	10.10
K	6.15BSC	
L	19.82	20.22
M	4.80	5.20
N	5.29	5.59
ØP	3.40	3.80

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